

THIS SHEET HAS BEEN
REPLACED

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ABSTRACT OF THE DISCLOSURE

5 A photoresist ashing residue cleaning agent used
after the ashing of the photoresist in the production of a
semiconductor circuit pattern. The photoresist ashing
residue cleaning agent comprises an aqueous solution
containing:

- a) an ammonium fluoride compound; and
- b) an amphoteric surfactant of which the cationic
10 group is an ammonium salt and of which the anionic group
is a carboxylate.

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